

Title (en)

METHOD FOR CONTINUOUS NICKEL-PLATING OF AN ALUMINIUM CONDUCTOR AND CORRESPONDING DEVICE

Title (de)

VERFAHREN ZUM KONTINUIERLICHEN VERNICKELN EINES ALUMINIUM-LEITERS UND VORRICHTUNG DAZU

Title (fr)

PROCEDE DE NICKELAGE EN CONTINU D'UN CONDUCTEUR EN ALUMINIUM ET DISPOSITIF CORRESPONDANT

Publication

**EP 1204787 B1 20050316 (FR)**

Application

**EP 00953251 A 20000718**

Priority

- FR 0002061 W 20000718
- FR 9909690 A 19990722

Abstract (en)

[origin: US6780303B2] A process for continuous nickel plating of an aluminum conductor, by electrolytically pre-treating the aluminum conductor to improve adherence of a nickel coat thereon by passing the aluminum conductor through a pre-treating bath in which is disposed an electrode connected to a first current source at a first voltage, for supplying to the aluminum conductor a pre-treating current, then electrolytically plating the pre-treated aluminum conductor with nickel in a plating bath in which is disposed an anode connected to a second current source at a second voltage, in which a nickel coat is deposited on the conductor by action of a nickel plating current  $I_n$ . At least the nickel plating current  $I_n$  is transmitted to the conductor through a mechanical electrical contact which contacts the conductor between the pre-treating bath and the plating bath, the pre-treating improving the contact properties of the conductor sufficient to permit the transmitting through the mechanical electrical conductor.

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